**Table S4.** Results of AOP analyses for major 190 chemicals.

Diethanolamine 111-42-2 photoresist layers a and development of an development of an development of the processing of th	
Dreast cancer  2.2:6.6-Tetrabromobisphenol A 79-94-7 component manufication of the processing and the proces	nductor
Acetaldehyde 75-07-0 Mold, Chip assemi Antimony trichloride 10025-91-9 Semiconductor M. Assemic trioxide 1327-53-3 Semiconductor M. Bisphenol A 80-05-7 Packaging Catechol 120-80-9 Wafer processing. Stripper: Used to r. photoresist layers i and development of CVD. Dry etching for implantation of Glycerol 56-81-5 Solder ball attachn n-Buryl alcohol 71-36-3 Semiconductor M. Perfluorooctane sulfonic acid 1763-23-1 Photomicrolithogra Phenol 108-95-2 Mold, Chip assemi Prench Phenol 108-95-2 Mold, Chip assemi I-Methoxy-2-propanol 107-98-2 Wafer processing. Smill Molecule Se Blocks  1-initronaphthalene 86-57-7 Semiconductor M. Perfluoro-2-methylphenol 1570-64-5 Semiconductor M. Diethylene glycol monobutyl ether 112-34-5 Semiconductor M. Diethylene glycol monobutyl ether 112-34-5 Semiconductor M. Diethylene glycol monobutyl ether 112-34-5 Semiconductor M. Dimethyl acetamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor M. Dimethyl acetamide 127-19-5 Photo (Diluent) Methyl-3-methoxy propionate 110-85-0 Chip assembly, Re Tetramethyl ammonium hydroside 5Crilhydrate) (developer), Rear of Marufacture of Semiconductor M. Piperazine 110-85-0 Chip assembly, Re Tetramethyl ammonium hydroside 5Crilhydrate) (developer), Rear of Marufacture of Semiconductor M. Piperazine 110-85-0 Chip assembly, Re Tetramethyl ammonium hydroside 5Crilhydrate) (developer), Rear of Marufacture of Semiconductor M. Piperazine 110-85-0 Chip assembly, Re Marufacture of Semiconductor M. Semiconductor M. Marufacture of Semiconductor M. Maruf	
Antimony trichloride 10025-91-9 Semiconductor Mr. Bisphenol A 80-05-7 Packaging Catechol 120-80-9 Wafer processing. Stripper: Used to photoresist slayers and development of photoresist slayers and development of CVD, Dry etching, Ion implantation Glycerol 56-81-5 Solder ball attachn n-Butyl alcohol 71-36-3 Semiconductor Mr. Perfluorocatane sulfonic acid 1763-23-1 Photomicrollibogr Phenol 108-95-2 Mold, Chip assembly alcohol 127-18-4 Mold, Chip assembly alcohol 127-18-4 Mold, Chip assembly alcohol 107-98-2 Wafer processing. Linitronaphthalene 86-57-7 Semiconductor Mr. Semiconductor Mr. Perfluorocatane sulfonic acid 107-98-2 Wafer processing. Linitronaphthalene 86-57-7 Small Molecule Sc. Blocks 2-Methoxyethanol 109-86-4 Manufacture of warmanufacturing 4-Chloro-2-methylphenol 1570-64-5 Semiconductor Mr. Diethylene glycol monobutyl ether Diethylene	nbly
Arsenic trioxide Bisphenol A B0-05-7 Packaging Catechol 120-80-9 Wafer processing, Stripper: Used to read and development of an and development of an analysis along the photoresis layers of an add evelopment of an analysis layers of an analysis l	bly
Bisphenol A 80.05-7 Packaging Catechol 120-80-9 Wafer processing. Stripper: Used to r Diethanolamine 111-42-2 photoresist layers a and development of CVD, Dry etching Ion implantation Glycerol 56-81-5 Solder ball attachn n-Butyl alcohol 71-36-3 Semiconductor Mr. Perfluorooctane sulfonic acid 1763-23-1 Photomicrolthogr Phenol 108-95-2 Mold, Chip assentl Tetrachforotethylene 127-18-4 Mold, Chip assentl I-Methoxy-2-propanol 107-98-2 Wafer processing. Small Molecule Sc Blocks  2-Methoxyethanol 109-86-4 Manufacture of we manufacturing 4-Chioro-2-methylphenol 1570-64-5 Semiconductor Mr. Diethylene glycol monobutyl ether Diethylene glycol monobutyl ether Dimethyl acetamide 127-19-5 Photo (Dituent) Nitrobenzene 98-95-3 Semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Dituent) Nitrobenzene 98-95-3 Semiconductor Mr. Manufacture of semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Dituent) Nitrobenzene 98-95-3 Semiconductor Mr. Manufacture of semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Dituent) Nitrobenzene 98-95-3 Semiconductor Mr. Manufacture of semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Dituent) Nitrobenzene 98-95-3 Semiconductor Mr. Chip assembly, Re 75-59-2 10424-66- Tetramethyl ammonium hydroxide 552-30-7  Trimelliic anhydride 552-30-7	nufacturing
Catechol 120-80-9 Wafer processing, Stripper: Used to r photoresist layers and development of CVD, Dry etching, Ion implantation on implantation of Glycerol 56-81-5 Solder ball attachn n-Butyl alcohol 71-36-3 Semiconductor Mr. Phenol 108-95-2 Mold, Chip assembly Rechord for the Manufacture of Semiconductor Mr. Landthoroethylene 127-18-4 Mold, Chip adhesis Zinc chloride fume 7646-85-7 Semiconductor Mr. Landthoroethylene 109-86-4 Wafer processing, Small Molecule Semiconductor of Mr. Landthoroethylene 109-86-4 Manufacture of war manufacturing 4-Chloro-2-methylphenol 1570-64-5 Semiconductor Mr. Diethylene glycol monobutyl ether 112-34-5 Semiconductor Mr. Diethyla ectamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Diluent) Mr. Diethyla ectamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Mr. Dimethyl arethyla ectamide 109-86-4 Mr. Manufacture of semiconductor Mr. Diethyla ectamide 109-86-4 Mr. Diethyla entomiconductor Mr. Diethyla ectamide 109-86-4 Mr.	nufacturing
Diethanolamine  Diethanolamine  Diethanolamine  Diethanolamine  Ethylene glycol  Glycerol  Glycerol  Glycerol  Glycerol  Ferfluorooctane sulfonic acid  Perfluorooctane sulfonic acid  Per	
Diethanolamine 111-42-2 photoresist layers and development of and development of and development of the processing and development of the proc	Photo/PR removal
Ethylene glycol  Glycerol	emove unnecessary ufter photo-resist pattern uring photo processing
Perfluorooctane sulfonic acid   17-36-3   Semiconductor Mz	Wafer processing,
Perfluorooctane sulfonic acid 1763-23-1 Photomicrolithogri Phenol 108-95-2 Mold, Chip assemi Tetrachloroethylene 127-18-4 Mold, Chip assemi Tetrachloroethylene 127-18-4 Mold, Chip adhesis Zinc chloride fume 7646-85-7 Semiconductor Mr. 1-Methoxy-2-propanol 107-98-2 Wafer processing, Small Molecule Sc Blocks Manufacture of warm manufacturing 4-Chloro-2-methylphenol 1570-64-5 Semiconductor Mr. Diethylene glycol monobutyl ether 112-34-5 Semiconductor Mr. Diethylene glycol monobutyl ether 112-34-5 Semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Mr. Indium phosphide 22398-80-7 Manufacture of ser Methyl-3-methoxy propionate 3852-09-3 Wafer processing, Piperazine 110-85-0 Chip assembly, Re 75-59-2 10424-66- 4(Pentahydrate) Trimellitic anhydride 552-30-7 -	nent, Chip assembly
Phenol 108-95-2 Mold, Chip assemt Tetrachloroethylene 127-18-4 Mold, Chip assemt Tetrachloroethylene 127-18-4 Mold, Chip adhesis Zinc chloride fume 7646-85-7 Semiconductor Mr. 1-Methoxy-2-propanol 107-98-2 Wafer processing, Small Molecule Se Blocks  1-nitronaphthalene 86-57-7 Small Molecule Se Blocks  2-Methoxyethanol 109-86-4 Manufacture of war manufacturing 4-Chloro-2-methylphenol 1570-64-5 Semiconductor Mr. Diethylene glycol monobutyl ether 112-34-5 Semiconductor Mr. Diethylene glycol monobutyl ether 112-34-5 Semiconductor Mr. Dimethyl acetamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Mr. Manufacture of semiconductor Mr. Mr. Mr. Mr. Mr. Mr. Mr. Mr. Mr. Mr	nufacturing
Tetrachloroethylene 127-18-4 Mold, Chip adhesis Zinc chloride fume 7646-85-7 Semiconductor Mr 1-Methoxy-2-propanol 107-98-2 Wafer processing, Small Molecule Se Blocks  1-nitronaphthalene 86-57-7 Small Molecule Se Blocks  2-Methoxyethanol 109-86-4 Manufacture of war manufacturing 4-Chloro-2-methylphenol 1570-64-5 Semiconductor Mr Diethylene glycol monobutyl ether 112-34-5 Semiconductor Mr Dimethyla cetamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Mr Indium phosphide 22398-80-7 Manufacture of semiconductor Mr Methyl-3-methoxy propionate 3852-09-3 Wafer processing, Piperazine 110-85-0 Chip assembly, Re 75-59-2 10424-66- 5(Trihydrate) (developer), Rear of 4(Pentahydrate) Trimellitic anhydride 552-30-7 -	aphy
Zinc chloride fume 1-Methoxy-2-propanol 107-98-2 Wafer processing, Small Molecule Se Blocks  2-Methoxyethanol 109-86-4 Manufacture of wa manufacturing  4-Chloro-2-methylphenol 1570-64-5 Semiconductor Me Diethylene glycol monobutyl ether Diethylene glycol monobutyl ether Dimethyl acetamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Me Dimethyl-3-methoxy propionate Methyl-3-methoxy propionate Methyl-3-methoxy propionate Tetramethyl ammonium hydroxide Trimellitic anhydride  Trimellitic anhydride  Trimellitic anhydride  Trimellitic anhydride  Trimellitic anhydride  Trimelitic anhydride  Manufacture of Manufacture of Securion Manufact	bly
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1-nitronaphthalene 86-57-7 Small Molecule Se Blocks  2-Methoxyethanol 109-86-4 Manufacture of wa manufacturing  4-Chloro-2-methylphenol 1570-64-5 Semiconductor Manufacturing  Diethylene glycol monobutyl ether 112-34-5 Semiconductor Manufacturing  Diethylene glycol monobutyl ether 112-34-5 Semiconductor Manufacturing  Dimethyl acetamide 127-19-5 Photo (Diluent)  Nitrobenzene 98-95-3 Semiconductor Manufacture of semicond	nufacturing
1-nitronaphthalene 86-57-7  Blocks  2-Methoxyethanol 109-86-4 Manufacture of wa manufacturing  4-Chloro-2-methylphenol 1570-64-5 Semiconductor Manufacturing  Diethylene glycol monobutyl ether 112-34-5 Semiconductor Manufacturing  Diethylene glycol monobutyl ether 112-34-5 Semiconductor Manufacturing  Dimethyl acetamide 127-19-5 Photo (Diluent)  Nitrobenzene 98-95-3 Semiconductor Manufacture of semiconductor Manufacture	Photo (PR solvent)
2-Methoxyethanol 109-86-4 manufacturing 4-Chloro-2-methylphenol 1570-64-5 Semiconductor Ma Diethylene glycol monobutyl ether 112-34-5 Semiconductor Ma Diethylene glycol monobutyl ether 112-34-5 Semiconductor Ma Dimethyl acetamide 127-19-5 Photo (Diluent) Nitrobenzene 98-95-3 Semiconductor Ma Indium phosphide 22398-80-7 Manufacture of ser Methyl-3-methoxy propionate 3852-09-3 Wafer processing, Piperazine 110-85-0 Chip assembly, Re 75-59-2 10424-66- Tetramethyl ammonium hydroxide 5(Trihydrate) (developer), Rear of the service o	miconductor Building
Diethylene glycol monobutyl ether  Diethylene glycol monobutyl ether  Diethylene glycol monobutyl ether  Dimethyl acetamide  Dimethyl acetamide  Dimethyl acetamide  127-19-5  Photo (Diluent)  Nitrobenzene  98-95-3  Semiconductor Ma  Indium phosphide  22398-80-7  Manufacture of ser  Methyl-3-methoxy propionate  3852-09-3  Wafer processing,  Piperazine  110-85-0  Chip assembly, Re  75-59-2  10424-66-  Tetramethyl ammonium hydroxide  Trimellitic anhydride  Trimellitic anhydride  552-30-7  -	fers for semiconductor
Diethylene glycol monobutyl ether  Dimethyl acetamide  Dimethyl acetamide  Dimethyl acetamide  127-19-5  Photo (Diluent)  Nitrobenzene  98-95-3  Semiconductor Ma  Judium phosphide  22398-80-7  Manufacture of ser  Methyl-3-methoxy propionate  3852-09-3  Wafer processing,  Piperazine  110-85-0  Chip assembly, Re  75-59-2  10424-66-  Tetramethyl ammonium hydroxide  Tetramethyl ammonium hydroxide  Trimellitic anhydride  Trimellitic anhydride  552-30-7  -	nufacturing
Dimethyl acetamide 127-19-5 Photo (Diluent)  Nitrobenzene 98-95-3 Semiconductor Ma  Indium phosphide 22398-80-7 Manufacture of set  Methyl-3-methoxy propionate 3852-09-3 Wafer processing,  Piperazine 110-85-0 Chip assembly, Re  75-59-2 10424-66- 5(Trihydrate) 10424-65- 4(Pentahydrate)  Trimellitic anhydride 552-30-7 -	nufacturing
Nitrobenzene 98-95-3 Semiconductor Ma Indium phosphide 22398-80-7 Manufacture of ser Methyl-3-methoxy propionate 3852-09-3 Wafer processing, Piperazine 110-85-0 Chip assembly, Re 75-59-2 10424-66- Tetramethyl ammonium hydroxide 5(Trihydrate) 10424-65- 4(Pentahydrate) Trimellitic anhydride 552-30-7 -	nufacturing
Indium phosphide 22398-80-7 Manufacture of ser  Methyl-3-methoxy propionate 3852-09-3 Wafer processing, Piperazine 110-85-0 Chip assembly, Re  75-59-2 10424-66- Tetramethyl ammonium hydroxide 5(Trihydrate) 10424-65- 4(Pentahydrate) Trimellitic anhydride 552-30-7 -	
Methyl-3-methoxy propionate 3852-09-3 Wafer processing, Piperazine 110-85-0 Chip assembly, Re 75-59-2 10424-66- Tetramethyl ammonium hydroxide 5(Trihydrate) 10424-65- 4(Pentahydrate) Trimellitic anhydride 552-30-7 -	nufacturing
Piperazine 110-85-0 Chip assembly, Re  75-59-2 10424-66- Tetramethyl ammonium hydroxide 5(Trihydrate) 10424-65- 4(Pentahydrate) Trimellitic anhydride 552-30-7 -	niconductor wafers
Tetramethyl ammonium hydroxide  Tetramethyl ammonium hydroxide  Trimellitic anhydride	Photo (PR solvent)
Tetramethyl ammonium hydroxide  10424-66- 5(Trihydrate) 10424-65- 4(Pentahydrate)  Trimellitic anhydride  552-30-7  -  Wafer processing, (developer), Rear of the state of the	ar Grinding
<u> </u>	Chip assembly, Photo Grinding
197 Antique autoritaide 21	
187 Anticoagulant rodenticide 31 Chemical Name CAS No. Process in Semicor	ductor
nhibition of vitamin K  2 poxide reductase resulting in 2 poxide reductase resulting in 3 poxide reductase resulting in 4 poxide reductase resulting in 5 poxide reductase resulting reductase resulting resulting resulting resulting resulting resulting res	
2,2',6,6'-Tetrabromobisphenol A 79-94-7 Semiconductor and electronic compone	
Acetaldehyde 75-07-0 Mold, Chip assembl	y
Acetone 67-64-1 Overall process, Mo Printing, Chip adhes	old, Wafer processing, sion, Chip assembly

Antimony trichloride	10025-91-9	Semiconductor Manufacturing
Arsenic trioxide	1327-53-3	Semiconductor Manufacturing
Bisphenol A	80-05-7	Packaging
Catechol	120-80-9	Wafer processing, Photo (PR removal)
Ethylene glycol	107-21-1	CVD, Dry etching, Wafer processing, Ion implantation
Isopropyl alcohol	67-63-0	Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent)
Methylchloro-isothiazolinone	26172-55-4	Semiconductor Manufacturing
Perfluorooctane sulfonic acid	1763-23-1	Photomicrolithography
Polyethylene polypropylene glycol	9003-11-6	Chip assembly
Pyrene	129-00-0	Ultra-high purity chemicals for Spin-On-Hard mask
Silica, amorphous	7631-86-9 112926-00-8	Polycrystalline silicon and silicon dioxide materials are etched in semiconductor manufacturing
Zinc chloride fume	7646-85-7	Semiconductor Manufacturing
1-Methoxy-2-propyl acetate	108-65-6	Wafer processing, Chip assembly, Photo (PR solvent)
2-Heptanone	110-43-0	Wafer processing, Photo (PR solvent)
4-Chloro-2-methylphenol	1570-64-5	Semiconductor Manufacturing
Epichlorohydrin	106-89-8	-
Heptane	142-82-5	Chip assembly, Mold etc.
Nitrobenzene	98-95-3	Semiconductor Manufacturing
Phosphoric acid	7664-38-2	Wafer processing, Wet etching
Piperazine	110-85-0	Chip assembly, Rear Grinding

60 NR1I2 (Pregnane X Receptor, PXR) activation leading to hepatic steatosis

Chemical Name	CAS No.	Process in Semiconductor	
2,2',6,6'-Tetrabromobisphenol A	79-94-7	Semiconductor and other electronic component manufacturing	
Bisphenol A	80-05-7	packaging	
Methylchloro-isothiazolinone	26172-55-4	Semiconductor Manufacturing	
Perfluorooctane sulfonic acid	1763-23-1	Photomicrolithography	
Polyethylene polypropylene glycol	9003-11-6	Chip assembly	
Pyrene	129-00-0	Ultra-high purity chemicals for Spin-On-Hard mask	
Tetrahydrofuran	109-99-9	Mold, Solder ball attachment, Chip assembly, Rear Grinding	
Zinc chloride fume	7646-85-7	Semiconductor Manufacturing	
1-nitronaphthalene	86-57-7	Small Molecule Semiconductor Building Blocks	
2-Methoxyethanol	109-86-4	Manufacture of wafers for semiconductor manufacturing	
Dimethyl acetamide	127-19-5	Photo (Diluent)	
Ethyl acetate	141-78-6	Chip assembly, Chip adhesion, Mold, Solder ball attachment, etc.	
Methyl isobutyl ketone	108-10-1	Chip assembly, Mold, etc.	
Chemical Name	CAS No.	Process in Semiconductor	

79-94-7

75-07-0

2,2',6,6'-Tetrabromobisphenol A

Acetaldehyde

Semiconductor and other

Mold, Chip assembly

electronic component manufacturing

36 Peroxisomal Fatty Acid Beta-Oxidation Inhibition leading to Steatosis 15

20

		A code codd	64 10 7	Washing Watching Wafer and a second
		Acetic acid	64-19-7	Washing, Wet etching, Wafer processing
		Antimony trichloride	10025-91-9	Semiconductor Manufacturing
		Bisphenol A	80-05-7	packaging  Westerness and the Plants (PR or least)
		2-Heptanone Phosphoric acid	110-43-0 7664-38-2	Wafer processing, Photo (PR solvent)  Wafer processing, Wet etching
		r nosphoric acid	7004-38-2	water processing, wer etching
58 NR1I3(CAR) suppression	15	Chemical Name	CAS No.	Process in Semiconductor
leading to hepatic steatosis		2,2',6,6'-Tetrabromobisphenol A	79-94-7	Semiconductor and other electronic component manufacturing
		2-Butoxyethanol	111-76-2	Overall Chip assembly
		Antimony trichloride	10025-91-9	Semiconductor Manufacturing
		Bisphenol A	80-05-7	Packaging
		Catechol	120-80-9	Wafer processing, Photo (PR removal)
		Cresol	o-Cresol 95-48-7 p-Cresol 106-44-5 m-Cresol 108-39-4	Mold, Wafer processing, Chip assembly, Photo (PR solvent)
		Diethanolamine	111-42-2	Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing
		Dimethylformamide	68-12-2	Mold
		Perfluorooctane sulfonic acid	1763-23-1	Photomicrolithography
		Phenol	108-95-2	Mold, Chip assembly
		Zinc chloride fume	7646-85-7	Semiconductor Manufacturing
66 Modulation of Adult	13	Chemical Name	CAS No.	Process in Semiconductor
Leydig Cell Function Subsequent Glucocorticoid		2,2',6,6'-Tetrabromobisphenol A	79-94-7	Semiconductor and other electronic component manufacturing
Activation in the Fetal Testis		Acetaldehyde	75-07-0	Mold, Chip assembly
		Antimony trichloride	10025-91-9	Semiconductor Manufacturing
		Bisphenol A	80-05-7	Packaging
		Catechol	120-80-9	Wafer processing, Photo (PR removal)
		Glycerol	56-81-5	Solder ball attachment, Chip assembly
		Perfluorooctane sulfonic acid	1763-23-1	Photomicrolithography
		Pyrene	129-00-0	Ultra-high purity chemicals for Spin-On-Hard mask
		Zinc chloride fume	7646-85-7	Semiconductor Manufacturing
107 Constitutive androstane	13	Chemical Name	CAS No.	Process in Semiconductor
receptor activation leading to		2016617711114	70.04.7	Semiconductor and other
nepatocellular adenomas and		2,2',6,6'-Tetrabromobisphenol A	79-94-7	electronic component manufacturing
carcinomas in the mouse and		Acetaldehyde	75-07-0	Mold, Chip assembly
he rat		Bisphenol A	80-05-7	Packaging
		Catechol	120-80-9	Wafer processing, Photo (PR removal)
		Perfluorooctane sulfonic acid	1763-23-1	Photomicrolithography
		Pyrene	129-00-0	Ultra-high purity chemicals for Spin-On-Hard mask
		1-nitronaphthalene	86-57-7	Small Molecule Semiconductor Building Blocks
		2-(2-Aminoethoxy)-ethanol	929-06-6	Wafer processing
		2-(2-Aminoethoxy)-ethanol Piperazine	929-06-6 110-85-0	Wafer processing Chip assembly, Rear Grinding

		2,2',6,6'-Tetrabromobisphenol A	79-94-7	Semiconductor and other electronic component manufacturing
		Acetaldehyde	75-07-0	Mold, Chip assembly
		Antimony trichloride	10025-91-9	Semiconductor Manufacturing
		Bisphenol A	80-05-7	Packaging
		Catechol	120-80-9	Wafer processing, Photo (PR removal)
		Cresol	o-Cresol 95-48-7 p-Cresol 106-44-5 m-Cresol 108-39-4	Mold, Wafer processing, Chip assembly, Photo (PR solvent)
		Isopropyl alcohol	67-63-0	Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent)
		Zinc chloride fume	7646-85-7	Semiconductor Manufacturing
		2-Heptanone	110-43-0	Wafer processing, Photo (PR solvent)
150 Aryl hydrocarbon	12	Chemical Name	CAS No.	Process in Semiconductor
receptor activation leading to		Bisphenol A	80-05-7	Packaging
early life stage mortality, via		Catechol	120-80-9	Wafer processing, Photo (PR removal)
reduced VEGF		Dimethyl sulfoxide	67-68-5	Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing
		Methylchloro-isothiazolinone	26172-55-4	Semiconductor Manufacturing
		Pyrene	129-00-0	Ultra-high purity chemicals for Spin-On-Hard mask
		Zinc chloride fume	7646-85-7	Semiconductor Manufacturing
		1-Methoxy-2-propyl acetate	108-65-6	Wafer processing, Chip assembly, Photo (PR solvent)
		1-nitronaphthalene	86-57-7	Small Molecule Semiconductor Building Blocks
		1-Nitropropane	108-03-2	Semiconductor Manufacturing
153 Aromatase Inhibition	12	Chemical Name	CAS No.	Process in Semiconductor
leading to Ovulation Inhibition and Decreased		2,2',6,6'-Tetrabromobisphenol A	79-94-7	Semiconductor and other
Fertility in Female Rats				electronic component manufacturing
Fertility in Female Rats		Acetaldehyde	75-07-0	Mold, Chip assembly
Fertility in Female Rats		Acetaldehyde Catechol	75-07-0 120-80-9	
Fertility in Female Rats				Mold, Chip assembly
Fertility in Female Rats		Catechol	120-80-9	Mold, Chip assembly Wafer processing, Photo (PR removal) Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning
Fertility in Female Rats		Catechol  Dimethyl sulfoxide	120-80-9 67-68-5	Mold, Chip assembly  Wafer processing, Photo (PR removal)  Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing  Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo
Fertility in Female Rats		Catechol  Dimethyl sulfoxide  Isopropyl alcohol	120-80-9 67-68-5 67-63-0	Mold, Chip assembly Wafer processing, Photo (PR removal) Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent)
163 PPARgamma activation	10	Catechol  Dimethyl sulfoxide  Isopropyl alcohol  Perfluorooctane sulfonic acid	120-80-9 67-68-5 67-63-0 1763-23-1	Mold, Chip assembly  Wafer processing, Photo (PR removal)  Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing  Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent)  Photomicrolithography
	10	Catechol  Dimethyl sulfoxide  Isopropyl alcohol  Perfluorooctane sulfonic acid  Diethylene glycol monobutyl ether	120-80-9 67-68-5 67-63-0 1763-23-1 112-34-5	Mold, Chip assembly Wafer processing, Photo (PR removal) Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent) Photomicrolithography Semiconductor Manufacturing
163 PPARgamma activation leading to sarcomas in rats,	10	Catechol  Dimethyl sulfoxide  Isopropyl alcohol  Perfluorooctane sulfonic acid Diethylene glycol monobutyl ether  Chemical Name	120-80-9 67-68-5 67-63-0 1763-23-1 112-34-5 CAS No.	Mold, Chip assembly Wafer processing, Photo (PR removal) Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent) Photomicrolithography Semiconductor Manufacturing  Process in Semiconductor  Semiconductor and other
163 PPARgamma activation leading to sarcomas in rats,	10	Catechol  Dimethyl sulfoxide  Isopropyl alcohol  Perfluorooctane sulfonic acid  Diethylene glycol monobutyl ether  Chemical Name  2,2',6,6'-Tetrabromobisphenol A	120-80-9 67-68-5 67-63-0 1763-23-1 112-34-5 CAS No.	Mold, Chip assembly  Wafer processing, Photo (PR removal)  Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing  Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent)  Photomicrolithography Semiconductor Manufacturing  Process in Semiconductor  Semiconductor and other electronic component manufacturing
163 PPARgamma activation leading to sarcomas in rats,	10	Catechol  Dimethyl sulfoxide  Isopropyl alcohol  Perfluorooctane sulfonic acid Diethylene glycol monobutyl ether  Chemical Name  2,2',6,6'-Tetrabromobisphenol A  Acetaldehyde	120-80-9 67-68-5 67-63-0 1763-23-1 112-34-5 CAS No.	Mold, Chip assembly Wafer processing, Photo (PR removal) Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent) Photomicrolithography Semiconductor Manufacturing  Process in Semiconductor  Semiconductor and other electronic component manufacturing Mold, Chip assembly
163 PPARgamma activation leading to sarcomas in rats,	10	Catechol  Dimethyl sulfoxide  Isopropyl alcohol  Perfluorooctane sulfonic acid Diethylene glycol monobutyl ether  Chemical Name  2,2',6,6'-Tetrabromobisphenol A  Acetaldehyde Bisphenol A	120-80-9 67-68-5 67-63-0 1763-23-1 112-34-5 CAS No. 79-94-7 75-07-0 80-05-7	Mold, Chip assembly Wafer processing, Photo (PR removal) Stripper: Used to remove unnecessary photoresist layers after photo-resist patterning and development during photo processing Washing, Cleaning solution (PM), Wafer processing, Maintenance, Chip assembly, Photo (PR solvent) Photomicrolithography Semiconductor Manufacturing  Process in Semiconductor  Semiconductor and other electronic component manufacturing Mold, Chip assembly Packaging

Blocks

Etc. minor -